

L I M I T E D T E N D E R
N O T I C E

Tender Ref. No.
PUR-12/24/2019-MCAD_DIV_SAM_CHENNAI-7484

Date
11.07.2019

Tender Due Date
25.07.2019

To

Dear Sir,

The Purchase Officer, SAMEER-Centre for Electromagnetics invites sealed tender for the supply of materials as per details given below:

Sl.No	Description of Items	Qty. Nos.
1	PCB Fabrication on Rogers material [8 Layer Board] (Specification List attached)	5 Nos

Terms and Conditions

- Price quoted should be on the basis of Destination delivery at Perungudi Campus, Chennai 600 096.
- Delivery / Completion period should be clearly indicated.
- Excise Duty, GST Percentage should be clearly indicated if admissible. Not eligible for FORM 'C' / 'D'
- WE ARE EXEMPTED FROM EXCISE DUTY
- Quotation should be valid for atleast 60 days from the date of opening of the tender
- Quotation should be sent in sealed envelope super scribing the tender reference number and tender due date. YOUR OFFER WILL NOT BE CONSIDERED IF OUR TENDER REFERENCE NO. & TENDER DUE DATE IS NOT MENTIONED ON COVER.
- Late tenders will not be accepted under any circumstances
- We reserve the right to accept or reject any quotations fully or partly without assigning any reasons.
- For Further Clarification Please Contact 044-22544061 / 22544020 Email:
purchase.chn.sameer@nic.in
- Unsolicited bids shall not be considered

(Handwritten Signature)
11/7/19

(P.Ramamoorthi)
Head – Administration
Contd...



ELECTRONICS INDIA

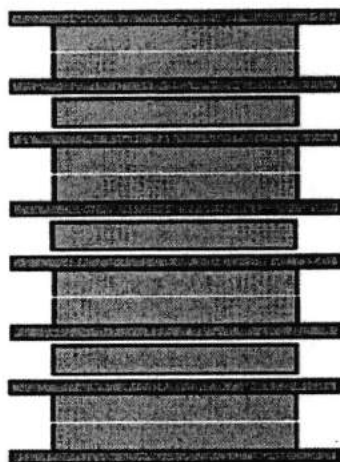
CIT Campus, 2nd Cross Road, Taramani, Chennai - 600 113, India

सी.आई.टी.परीसर, दूसरा क्रॉस रोड, तारामणी चेन्नै - ६०० ११३.

दूरवचन : Tel : +91-44-22541583 / 1817 / 2106 / 2452 फैक्स / Fax : 2254 1938 / 1424

वेबसाईट / web: <http://www.sameer.gov.in> ई-मेल / E-mail : pd@cem.sameer.gov.in

SL No	Specification	Requirement	Compliance
1	Board Thickness	1.63 mm	
2	Thickness tolerance	+/- 10 %	
3	No of Layers	8 Layers	
4	Board Size	72 x 54 mm	
5	Substrate materials	Rogers 4350B, 10 mil, Rogers 4003C, 8 mil	
6	Preperg Material	Rogers 4450F, 8 mil	
7	Layer Stack up	Given Below	
8	Through Hole Via - Size, Count	0.6 , 0.4 mm – 464 Total	
9	Blind Via – Size, Count	0.35, 0.4, 0.6 mm – 731 Total	
10	Surface finish	ISIG / ENIPIG / ENEPIG	
11	Buried Via	NONE	
12	Minimum track width	0.25 mm	
13	Minimum spacing	0.18 mm	
14	Copper Thickness	18 Micron	
15	Solder Mask	Required	
16	Silk Screen	Required	
17	Via on PAD	Yes	
18	Via Filling	Not Required	
19	Edge Plating	Not Required	
20	Fabrication file Format	Gerber files -RS274X format	
21	Impedance Control	NA	
22	Electrical testing	Required	
23	Quantity	5 Nos	
24	Lead Time	25 Days	



Rogers 4003C, 8 mil Thickness

Rogers Prepreg 4450F, 8 mil Thickness

Rogers 4350B, 10 mil Thickness

Rogers Prepreg 4450F, 8 mil Thickness

Rogers 4350B, 10 mil Thickness

Rogers Prepreg 4450F, 8 mil Thickness

Rogers 4003C, 8 mil Thickness